

Title (en)
SEMICONDUCTOR CHIP ASSEMBLY AND METHOD OF PREPARING THE SAME

Title (de)
HALBLEITERCHIPANORDNUNG UND VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)
ENSEMBLE PUCE À SEMI-CONDUCTEURS ET SON PROCÉDÉ DE PRÉPARATION

Publication
EP 2606509 A4 20150916 (EN)

Application
EP 11819399 A 20110816

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Abstract (en)
[origin: WO2012025024A1] A semiconductor chip assembly and a method for forming the same are provided. The semiconductor chip assembly comprises: a semiconductor chip (20), a substrate (10), a first layer (203) formed on a surface of the substrate (10), in which one of the first layer (203) and the second layer (204) has an opening (205) therein; and a second layer (204) formed on a surface of the semiconductor chip (20) and connected to the first layer (203) by eutectic bonding.

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Citation (search report)
• [X] EP 0313174 A2 19890426 - SUMITOMO ELECTRIC INDUSTRIES [JP]
• [X] JP 2006128254 A 20060518 - HITACHI MEDIA ELECTRON KK
• [XI] GB 1581436 A 19801217 - EMI LTD
• See references of WO 2012025024A1

Designated contracting state (EPC)
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